ABSTRACT

This application report demonstrates the use of TI's Smart Bypass Diode- SM74611 as a high efficiency solution for use in N+1 redundant power supply arrangements. It highlights the ease of use, high efficiency and unique technology applied in this approach.

<table>
<thead>
<tr>
<th>Contents</th>
<th></th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>Introduction</td>
</tr>
<tr>
<td>1.1</td>
<td>OR-ing Controller Requirement</td>
</tr>
<tr>
<td>1.2</td>
<td>Solution Approaches</td>
</tr>
<tr>
<td>1.3</td>
<td>Limitations:</td>
</tr>
<tr>
<td>2</td>
<td>SM74611</td>
</tr>
<tr>
<td>2.1</td>
<td>Working</td>
</tr>
<tr>
<td>2.2</td>
<td>Advantages of SM74611</td>
</tr>
<tr>
<td>3</td>
<td>Test Results</td>
</tr>
<tr>
<td>4</td>
<td>Conclusion</td>
</tr>
<tr>
<td>5</td>
<td>References</td>
</tr>
</tbody>
</table>

List of Figures

<table>
<thead>
<tr>
<th>Figure</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>Schottky Diodes used for OR-ing</td>
</tr>
<tr>
<td>2</td>
<td>MOSFETs used along with OR-ing controllers</td>
</tr>
<tr>
<td>3</td>
<td>Internal Block Diagram of SM74611</td>
</tr>
<tr>
<td>4</td>
<td>Waveform showing ANODE to CATHODE voltage (Ch1) with Ibypass= 15 A (Ch4) in Junction Box at 85°C</td>
</tr>
<tr>
<td>5</td>
<td>Startup Waveform</td>
</tr>
<tr>
<td>6</td>
<td>Turnoff Waveform</td>
</tr>
<tr>
<td>7</td>
<td>Voltage Difference = 0.5 V</td>
</tr>
<tr>
<td>8</td>
<td>Voltage Difference = 0.3 V</td>
</tr>
<tr>
<td>9</td>
<td>Voltage Difference = 0.2 V</td>
</tr>
<tr>
<td>10</td>
<td>Voltage Difference = 0.1 V</td>
</tr>
<tr>
<td>11</td>
<td>Voltage Difference = 0 V</td>
</tr>
<tr>
<td>12</td>
<td>Voltage Difference = 460 mV</td>
</tr>
<tr>
<td>13</td>
<td>Reverse Current</td>
</tr>
</tbody>
</table>
1 Introduction

The SM74611 is Texas Instruments Smart Bypass Diode which externally connects as a regular 2-pin Schottky diode but offers a lesser forward voltage drop. It has a typical average forward voltage drop of 26 mV at 8 A of current. Taking the example of a 12 V, 8 A power supply, the 26 mV drop translates to a typical power dissipation of 208 mW. The SM74611 is also footprint and pin-compatible with conventional D2PAK Schottky diodes, making it a drop-in replacement in many applications.

This device supports a maximum forward current of 15 A.

1.1 OR-ing Controller Requirement

Systems that require high availability or need to choose between more than one simultaneously available power sources often use multiple, parallel-connected redundant power supplies to improve reliability. Common examples of such systems are telecom power supplies where the AC line supply is supplemented with the battery backup supply. Another good example can be portable devices where the supply can be derived either from a line supply, USB port, or a storage battery.

These supplies, typically being voltage sources, have very low output impedance, and are all active simultaneously. Therefore, they cannot be directly shorted. To prevent the output of a higher voltage supply from loading the rest, the outputs need to be connected such that the conduction path is unidirectional.

1.2 Solution Approaches

The simplest approach is using Schottky OR-ing diodes to connect these redundant power supplies to a common point at the load. The disadvantage of using Schottky diodes is forward voltage drop, which reduces the available voltage and the associated high power losses. These losses are significant at higher currents.

![Schottky Diodes used for OR-ing](image)

Using the example of the 12 V, 8 A supply, and assuming a forward voltage drop of 0.4 V, a total of 3.2 W is dissipated in the Schottky diode! This results in an unnecessary reduction in the efficiency of the supply. It becomes necessary, then, to handle the proper dissipation of this extra heat generated in the diode.
A solution to this problem can be the use of a MOSFET to replace the OR-ing diode. This requires a small increase in the level of complexity, but reduces -- or eliminates -- the need for diode heat sinks or a large thermal copper area in circuit board layouts for high power applications.

![MOSFETs used along with OR-ing controllers](image)

In the case of a positive voltage OR-ing controller, the voltage across the MOSFET source and drain pins is monitored and the GATE pin of the MOSFET is driven based on this detected voltage difference. The resulting behavior is that of an ideal rectifier with source and drain pins of the MOSFET acting as anode and cathode pins of a diode respectively.

When power is initially applied, the load current will flow from source to drain through the body diode of the MOSFET. The resulting voltage across the body diode will be detected at the IN and OUT pins of the OR-ing controller which then begins charging the MOSFET gate to a voltage greater than the Source or IN pin voltage.

In the event that another slightly different voltage supply is connected to the common load point, the OUT pin voltage of the OR-ing controller driving the MOSFET (connected to the lower voltage supply) rises higher than the IN pin voltage. Once this condition is detected, the gate capacitance is discharged, effectively turning off the MOSFET and disconnecting the lower voltage supply.

### 1.3 Limitations:

Two of the major limitations with this implementation are:

1. The OR-ing controller requires an external supply for operation and utilizes the input supply for this purpose. This puts a restriction on the range of input supply voltage which may get reduced to a value less than that dictated by the MOSFET ratings.

2. This solution requires external MOSFETS which add complexity (albeit slight) to the solution when compared with simple diodes.
2.1 Working

Internally, the SM74611 utilizes a charge pump to drive an N-channel FET to provide an optional connection to the output load.

![Internal Block Diagram of SM74611](image)

The operation of the Smart Diode when used as an OR-ing controller can be explained in the following time slots:

**From t0 to t1:**
When the load is first connected to the supply, FET Q1 is off and the load current will flow through the body diode of the FET. This current will produce a voltage drop ($V_f$) across ANODE and CATHODE terminal of the bypass diode. During this time, the charge pump circuitry is active and charges capacitor C1 to a higher voltage.

**At t1:**
Once the voltage on the capacitor reaches its predetermined voltage level, the charge pump is disabled and the capacitor voltage is used to drive the FET through the FET driver stage.

**From t1 to t2:**
When the FET is active, it provides a low resistive path for the load current to flow, thus minimizing the power dissipation across ANODE and CATHODE. Since the FET is active, the voltage across the ANODE and CATHODE is too low to operate the charge pump. During this time, the stored charge on C1 is used to supply the controller as well as drive the FET.

**At t2:**
When the voltage on the capacitor C1 reaches its predetermined lower level, the FET driver shuts off the FET. The load current will then begin to flow through the body diode of the FET, causing the FET body diode voltage to drop to approximately 0.6 V across ANODE and CATHODE. The charge pump circuitry is reactivated and begins charging the capacitor C1. This cycle repeats.

The key factor to minimizing the power dissipation on the device is to keep the FET on at a high duty cycle. The average forward voltage drop of a Schottky or regular P-N junction diode. Figure 4 shows a diagram from the datasheet of the device which was measured for the solar panel application with a bypass current of 15 A. In fact, this operation is quite identical to the charge pump based OR-ing controllers which drive external MOSFETs as discussed earlier.
Figure 4. Waveform showing ANODE to CATHODE voltage (Ch1) with Ibypass= 15 A (Ch4) in Junction Box at 85°C

2.2 Advantages of SM74611

The SM74611 offers several advantages when used as an OR-ing device, such as:
1. Very low average forward voltage drop.
2. Very low power dissipation as compared to simple Schottky diodes.
3. Simple operation with maximum integration in device.
4. Footprint and pin compatible with conventional D2PAK Schottky diodes.
5. Low power dissipation, so heat sink is not required.
3 Test Results

1. Startup Waveform- Supply 1 takes over the load current demand. (10 A):

Ch1. Current output of supply 1 (0 A M 10 A)
Ch2. Voltage output of supply 1 (10 V)
Ch3. Voltage output of supply 2 (9 V)
Ch4. Output Voltage after OR-ing of supplies (9 V M 10 V)

Figure 5. Startup Waveform
2. Turnoff waveform- Supply 2 takes over the load current demand. (10 A):

Ch1. Current output of supply 1 (10 A M 0 A)
Ch2. Voltage output of supply 1 (9 V)
Ch3. Voltage output of supply 2 (10 V)
Ch4. Output Voltage after OR-ing of supplies (9 V M 10 V)

Figure 6. Turnoff Waveform
When we have two almost equal supplies, here is what is observed:

3. Voltage difference of 0.5 V (Notice the dips in the output voltage. This is the excess drop during the time slots which the forward diode conducts and charges the internal capacitor)

Figure 7. Voltage Difference = 0.5 V
4. Voltage difference of 0.3 V (Notice that the load current is getting shared between the two power supplies /reverse current into supply1)

Ch1. Current output of supply 1
Ch2. Voltage output of supply1 (10.3 V)
Ch3. Voltage output of supply 2 (10 V)
Ch4. Output Voltage after OR-ing of supplies

Figure 8. Voltage Difference = 0.3 V
5. Voltage difference of 0.2 V (Notice that the load current is getting shared between the two power supplies / reverse current into supply1)

Ch1. Current output of supply 1
Ch2. Voltage output of supply1 (10.2 V)
Ch3. Voltage output of supply 2 (10 V)
Ch4. Output Voltage after OR-ing of supplies

Figure 9. Voltage Difference = 0.2 V
6. Voltage difference of 0.1 V (Notice that the load current is getting shared between the two power supplies / reverse current into supply1)

Figure 10. Voltage Difference = 0.1 V
7. Voltage difference of 0 V (Notice that the load current is getting shared between the two power supplies / reverse current into supply1)

Figure 11. Voltage Difference = 0 V

Ch1. Current output of supply 1
Ch2. Voltage output of supply1 (10 V)
Ch3. Voltage output of supply 2 (10 V)
Ch4. Output Voltage after OR-ing of supplies
8. Min difference in power supply voltages required to trigger complete selection of one supply is observed to be about 460mV. This is just to give a rough idea and can vary from device to device:

Ch1. Current output of supply 1
Ch2. Voltage output of supply 1 (10 V)
Ch3. Voltage output of supply 2 (10 V)
Ch4. Output Voltage after OR-ing of supplies

Figure 12. Voltage Difference = 460 mV
9. Example of Reverse Current into Supply 1

Ch1. Current output of supply 1
Ch2. Voltage output of supply 1 (10 V)
Ch3. Voltage output of supply 2 (15 V)
Ch4. Output Voltage after OR-ing of supplies (10 V $\rightarrow$ 15 V)

Figure 13. Reverse Current
4 Conclusion

As demonstrated in this application report, the Smart Bypass Diode can easily and effectively be used as an OR-ing device. The low average forward voltage drop greatly reduces power dissipation, which is especially useful at high load currents. This helps in achieving better efficiencies and eliminates a heat sink requirement. The device can even be swapped with existing D2PAK Schottky diodes.

5 References

1. SM74611 datasheet: http://www.ti.com/product/sm74611
EVALUATION BOARD/KIT/MODULE (EVM) ADDITIONAL TERMS

Texas Instruments (TI) provides the enclosed Evaluation Board/Kit/Module (EVM) under the following conditions:

The user assumes all responsibility and liability for proper and safe handling of the goods. Further, the user indemnifies TI from all claims arising from the handling or use of the goods.

Should this evaluation board/kit not meet the specifications indicated in the User’s Guide, the board/kit may be returned within 30 days from the date of delivery for a full refund. THE FOREGOING LIMITED WARRANTY IS THE EXCLUSIVE WARRANTY MADE BY SELLER TO BUYER AND IS IN LIEU OF ALL OTHER WARRANTIES, EXPRESSED, IMPLIED, OR STATUTORY, INCLUDING ANY WARRANTY OF MERCHANTABILITY OR FITNESS FOR ANY PARTICULAR PURPOSE. EXCEPT TO THE EXTENT OF THE INDEMNITY SET FORTH ABOVE, NEITHER PARTY SHALL BE LIABLE TO THE OTHER FOR ANY INDIRECT, SPECIAL, INCIDENTAL, OR CONSEQUENTIAL DAMAGES.

Please read the User's Guide and, specifically, the Warnings and Restrictions notice in the User's Guide prior to handling the product. This notice contains important safety information about temperatures and voltages. For additional information on TI's environmental and/or safety programs, please visit www.ti.com/esh or contact TI.

No license is granted under any patent right or other intellectual property right of TI covering or relating to any machine, process, or combination in which such TI products or services might be or are used. TI currently deals with a variety of customers for products, and therefore our arrangement with the user is not exclusive. TI assumes no liability for applications assistance, customer product design, software performance, or infringement of patents or services described herein.

REGULATORY COMPLIANCE INFORMATION

As noted in the EVM User’s Guide and/or EVM itself, this EVM and/or accompanying hardware may or may not be subject to the Federal Communications Commission (FCC) and Industry Canada (IC) rules.

For EVMs not subject to the above rules, this evaluation board/kit/module is intended for use for ENGINEERING DEVELOPMENT, DEMONSTRATION OR EVALUATION PURPOSES ONLY and is not considered by TI to be a finished end product fit for general consumer use. It generates, uses, and can radiate radio frequency energy and has not been tested for compliance with the limits of computing devices pursuant to part 15 of FCC or ICES-003 rules, which are designed to provide reasonable protection against radio frequency interference. Operation of the equipment may cause interference with radio communications, in which case the user at his own expense will be required to take whatever measures may be required to correct this interference.

General Statement for EVMs including a radio

User Power/Frequency Use Obligations: This radio is intended for development/professional use only in legally allocated frequency and power limits. Any use of radio frequencies and/or power availability of this EVM and its development application(s) must comply with local laws governing radio spectrum allocation and power limits for this evaluation module. It is the user’s sole responsibility to only operate this radio in legally acceptable frequency space and within legally mandated power limitations. Any exceptions to this are strictly prohibited and unauthorized by Texas Instruments unless user has obtained appropriate experimental/development licenses from local regulatory authorities, which is responsibility of user including its acceptable authorization.

For EVMs annotated as FCC – FEDERAL COMMUNICATIONS COMMISSION Part 15 Compliant

Caution

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation. Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

FCC Interference Statement for Class A EVM devices

This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.
FCC Interference Statement for Class B EVM devices

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

For EVMs annotated as IC – INDUSTRY CANADA Compliant

This Class A or B digital apparatus complies with Canadian ICES-003.

Changes or modifications not expressly approved by the party responsible for compliance could void the user’s authority to operate the equipment.

Concerning EVMs including radio transmitters

This device complies with Industry Canada licence-exempt RSS standard(s). Operation is subject to the following two conditions: (1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

Concerning EVMs including detachable antennas

Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication.

This radio transmitter has been approved by Industry Canada to operate with the antenna types listed in the user guide with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

Cet appareil numérique de la classe A ou B est conforme à la norme NMB-003 du Canada.

Les changements ou les modifications pas expressément approuvés par la partie responsable de la conformité ont pu vider l’autorité de l’utilisateur pour actionner l’équipement.

Concernant les EVMs avec appareils radio

Le présent appareil est conforme aux CNR d’Industrie Canada applicables aux appareils radio exempts de licence. L’exploitation est autorisée aux deux conditions suivantes : (1) l’appareil ne doit pas produire de brouillage, et (2) l’utilisateur de l’appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d’en compromettre le fonctionnement.

Concernant les EVMs avec antennes détachables

Conformément à la réglementation d’Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d’un type et d’un gain maximal (ou inférieur) approuvé pour l’émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l’intention des autres utilisateurs, il faut choisir le type d’antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l’intensité nécessaire à l’établissement d’une communication satisfaisante.

Le présent émetteur radio a été approuvé par Industrie Canada pour fonctionner avec les types d’antenne énumérés dans le manuel d’usage et ayant un gain admissible maximal et l’impédance requise pour chaque type d’antenne. Les types d’antenne non inclus dans cette liste, ou dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l’exploitation de l’émetteur.
【Important Notice for Users of EVMs for RF Products in Japan】

This development kit is NOT certified as Confirming to Technical Regulations of Radio Law of Japan

If you use this product in Japan, you are required by Radio Law of Japan to follow the instructions below with respect to this product:

1. Use this product in a shielded room or any other test facility as defined in the notification #173 issued by Ministry of Internal Affairs and Communications on March 28, 2006, based on Sub-section 1.1 of Article 6 of the Ministry’s Rule for Enforcement of Radio Law of Japan,
2. Use this product only after you obtained the license of Test Radio Station as provided in Radio Law of Japan with respect to this product, or
3. Use of this product only after you obtained the Technical Regulations Conformity Certification as provided in Radio Law of Japan with respect to this product. Also, please do not transfer this product, unless you give the same notice above to the transferee. Please note that if you could not follow the instructions above, you will be subject to penalties of Radio Law of Japan.

Texas Instruments Japan Limited
(address) 24-1, Nishi-Shinjuku 6 chome, Shinjuku-ku, Tokyo, Japan

http://www.tij.co.jp

【無線電波を送信する製品の開発キットをお使いになる際の注意事項】

本開発キットは技術基準適合証明を受けておりません。

本製品のご使用に際しては、電波法遵守のため、以下のいずれかの措置を取っていただく必要がありますのでご注意ください。
1. 電波法施行規則第6条第1項第1号に基づく平成18年3月28日総務省告示第173号で定められた電波暗室等の試験設備でご使用いただく。
2. 実験局の免許を取得後ご使用いただく。
3. 技術基準適合証明を取得後ご使用いただく。

なお、本製品は、上記の「ご使用にあたっての注意」を譲渡先、移転先に通知しない限り、譲渡、移転できないものとします。

日本テキサス・インスツルメンツ株式会社
東京都新宿区西新宿6丁目24番1号
西新宿三井ビル
http://www.tij.co.jp
EVALUATION BOARD/KIT/MODULE (EVM)
WARNINGS, RESTRICTIONS AND DISCLAIMERS

For Feasibility Evaluation Only, in Laboratory/Development Environments. Unless otherwise indicated, this EVM is not a finished electrical equipment and not intended for consumer use. It is intended solely for use for preliminary feasibility evaluation in laboratory/development environments by technically qualified electronics experts who are familiar with the dangers and application risks associated with handling electrical mechanical components, systems and subsystems. It should not be used as all or part of a finished end product.

Your Sole Responsibility and Risk. You acknowledge, represent and agree that:

1. You have unique knowledge concerning Federal, State and local regulatory requirements (including but not limited to Food and Drug Administration regulations, if applicable) which relate to your products and which relate to your use (and/or that of your employees, affiliates, contractors or designees) of the EVM for evaluation, testing and other purposes.
2. You have full and exclusive responsibility to assure the safety and compliance of your products with all such laws and other applicable regulatory requirements, and also to assure the safety of any activities to be conducted by you and/or your employees, affiliates, contractors or designees, using the EVM. Further, you are responsible to assure that any interfaces (electronic and/or mechanical) between the EVM and any human body are designed with suitable isolation and means to safely limit accessible leakage currents to minimize the risk of electrical shock hazard.
3. Since the EVM is not a completed product, it may not meet all applicable regulatory and safety compliance standards (such as UL, CSA, VDE, CE, RoHS and WEEE) which may normally be associated with similar items. You assume full responsibility to determine and/or assure compliance with any such standards and related certifications as may be applicable. You will employ reasonable safeguards to ensure that your use of the EVM will not result in any property damage, injury or death, even if the EVM should fail to perform as described or expected.
4. You will take care of proper disposal and recycling of the EVM's electronic components and packing materials.

Certain Instructions. It is important to operate this EVM within TI’s recommended specifications and environmental considerations per the user guidelines. Exceeding the specified EVM ratings (including but not limited to input and output voltage, current, power, and environmental ranges) may cause property damage, personal injury or death. If there are questions concerning these ratings please contact a TI field representative prior to connecting interface electronics including input power and intended loads. Any loads applied outside of the specified output range may result in unintended and/or inaccurate operation and/or possible permanent damage to the EVM and/or interface electronics. Please consult the EVM User's Guide prior to connecting any load to the EVM output. If there is uncertainty as to the load specification, please contact a TI field representative. During normal operation, some circuit components may have case temperatures greater than 60°C as long as the input and output are maintained at a normal ambient operating temperature. These components include but are not limited to linear regulators, switching transistors, pass transistors, and current sense resistors which can be identified using the EVM schematic located in the EVM User's Guide. When placing measurement probes near these devices during normal operation, please be aware that these devices may be very warm to the touch. As with all electronic evaluation tools, only qualified personnel knowledgeable in electronic measurement and diagnostics normally found in development environments should use these EVMs.

Agreement to Defend, Indemnify and Hold Harmless. You agree to defend, indemnify and hold TI, its licensors and their representatives harmless from and against any and all claims, damages, losses, expenses, costs and liabilities (collectively, “Claims”) arising out of or in connection with any use of the EVM that is not in accordance with the terms of the agreement. This obligation shall apply whether Claims arise under law of tort or contract or any other legal theory, and even if the EVM fails to perform as described or expected.

Safety-Critical or Life-Critical Applications. If you intend to evaluate the components for possible use in safety critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, such as devices which are classified as FDA Class III or similar classification, then you must specifically notify TI of such intent and enter into a separate Assurance and Indemnity Agreement.
IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as “components”) are sold subject to TI’s terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI’s terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers’ products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers’ products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI’s goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or “enhanced plastic” are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have not been so designated is solely at the Buyer’s risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products

<table>
<thead>
<tr>
<th>Audio</th>
<th><a href="http://www.ti.com/audio">www.ti.com/audio</a></th>
</tr>
</thead>
<tbody>
<tr>
<td>Amplifiers</td>
<td><a href="http://www.ti.com/amplifier">www.ti.com/amplifier</a></td>
</tr>
<tr>
<td>Data Converters</td>
<td><a href="http://www.ti.com/dataconverter">www.ti.com/dataconverter</a></td>
</tr>
<tr>
<td>DLP® Products</td>
<td><a href="http://www.ti.com/dlp">www.ti.com/dlp</a></td>
</tr>
<tr>
<td>DSP</td>
<td><a href="http://www.ti.com/dsp">www.ti.com/dsp</a></td>
</tr>
<tr>
<td>Clocks and Timers</td>
<td><a href="http://www.ti.com/clocks">www.ti.com/clocks</a></td>
</tr>
<tr>
<td>Interface</td>
<td><a href="http://www.ti.com/interface">www.ti.com/interface</a></td>
</tr>
<tr>
<td>Logic</td>
<td><a href="http://www.ti.com/logic">www.ti.com/logic</a></td>
</tr>
<tr>
<td>Power Mgmt</td>
<td><a href="http://www.ti.com/power">www.ti.com/power</a></td>
</tr>
<tr>
<td>Microcontrollers</td>
<td><a href="http://www.ti.com/microcontroller">www.ti.com/microcontroller</a></td>
</tr>
<tr>
<td>RFID</td>
<td><a href="http://www.ti.com/rfid">www.ti.com/rfid</a></td>
</tr>
<tr>
<td>OMAP Applications Processors</td>
<td><a href="http://www.ti.com/omap">www.ti.com/omap</a></td>
</tr>
<tr>
<td>Wireless Connectivity</td>
<td><a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a></td>
</tr>
</tbody>
</table>

Applications

| Automotive and Transportation | www.ti.com/automotive |
| Communications and Telecom | www.ti.com/communications |
| Computers and Peripherals | www.ti.com/computers |
| Consumer Electronics | www.ti.com/consumer-apps |
| Energy and Lighting | www.ti.com/energy |
| Industrial | www.ti.com/industrial |
| Medical | www.ti.com/medical |
| Security | www.ti.com/security |
| Space, Avionics and Defense | www.ti.com/space-avionics-defense |
| Video and Imaging | www.ti.com/video |

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2013, Texas Instruments Incorporated